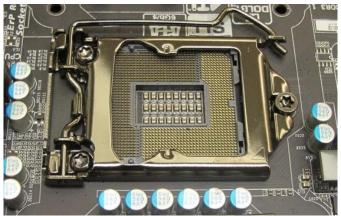
Written by Marco Attard 28 November 2012

If one is to believe a supposedly leaked Intel roadmap on Japanese website PC Watch, Intel might kill off a CPU standard-- the current Land Grid Array (LGA) socket will give way to Ball Grid Array (BGA).



The current LGA socket is an 8-year old technology where the actual contacts are on the motherboard while the contact points are on the CPU.

On the other hand BGA technology involves directly attaching chips on circuit boards via small balls of solder.

BGA is already used for DRAM, embedded CPUs and other surface-mount chips, but is more difficult to troubleshoot and repair-- and does not allow for PC CPU upgrades.

It would also mean the end of selling separate Intel CPUs and 3rd party motherboards, since OEMs would have to hard-mount CPUs themselves.

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